DESCRIPTION

~~SLURRY AND SLURRY MANUFACTURING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to slurry for use in a wire saw for slicing a workpiece, such as an ingot, and a method for producing the slurry.

BACKGROUND ART

[0002]

In recent years, wire saws have been used to slice workpieces, such as semiconductor materials, magnetic materials, and ceramic, in production processes of semiconductor wafers, solar cells for a solar battery, etc.

The wire saw is an apparatus for slicing a workpiece by imparting reciprocating motion to a wire, and pressing the workpiece against the wire while supplying slurry into which free abrasive grains, such as silicon carbide grains, are blended. The slurry may contain either an oil coolant or a water-soluble coolant, and the water-soluble coolant has recently become mainstream from the viewpoint of an environmental load, such as recycling and drain disposal after use.

[0003]

It is known that such a slicing process of a workpiece with a wire saw produces swarf, which becomes a material loss (a kerf loss), with a width corresponding to the sum of a wire diameter and about two to three times an abrasive grain diameter, and thinned wires or abrasive grains having smaller diameter are accordingly used to reduce the kerf loss (See Patent Document 1, for example).

[0004]

DESCRIPTION

SLURRY AND METHOD FOR PRODUCING SLURRY

TECHNICAL FIELD

[0001]

The present invention relates to slurry for use in a wire saw for slicing a workpiece, such as an ingot, and a method for producing the slurry.

BACKGROUND ART

[0002]

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[0004]